



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTF3125EJ	Issued	24. June 2021
MA#	MA005549598		
Package	PG-TDSO-8-31	Weight*	67.40 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.367	2.03	2.03	20284	20284
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		564	
	non noble metal	iron	7439-89-6	0.760	1.13		11273	
	non noble metal	copper	7440-50-8	30.851	45.78	46.98	457745	469723
wire	non noble metal	copper	7440-50-8	0.282	0.42	0.42	4189	4189
encapsulation	organic material	carbon black	1333-86-4	0.097	0.14		1434	
	plastics	epoxy resin	-	3.769	5.59		55921	
	inorganic material	silicondioxide	60676-86-0	28.347	42.06	47.79	420603	477958
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7378	7378
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12238	12238
glue	plastics	epoxy resin	-	0.097	0.14		1440	
	noble metal	silver	7440-22-4	0.458	0.68	0.82	6790	8230
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com